CLAIMS

What is claimed is:

1. An apparatus for preventing damage to a chamber wall by a baffle plate in a semiconductor fabrication system during a semiconductor fabrication operation, said apparatus comprising:

an electrostatic chuck associated with said semiconductor fabrication system;

a gauge for measuring a gap between said baffle plate and said chamber wall, hereby preventing damage to said chamber wall by said baffle plate during a movement of said electrostatic chunk during said semiconductor fabrication operation of said semiconductor fabrication system.

2. The apparatus of claim 1 wherein said semiconductor fabrication operation comprises a wet cleaning semiconductor operation.

3. The apparatus of claim 1 wherein said gauge is adapted for use in leveling said electrostatic chunk.

4. The apparatus of claim 1 wherein said gauge comprises a horizontal gap gauge.

5. The apparatus of claim 1 wherein said gauge is adapted for use in preventing polymer peeling of said chamber wall.

6. The apparatus of claim 1 wherein said gauge comprises a leveling gauge.

7. The apparatus of claim 1 wherein said semiconductor fabrication system comprises dual-rotate-magnet (DRM).

8. The apparatus of claim 7 wherein said semiconductor fabrication system comprises a focus ring.

9. The apparatus of claim 8 wherein said movement of said electrostatic chunk during said semiconductor fabrication operation comprises a vertical movement.

10. The apparatus of claim 8 wherein said movement of said electrostatic chunk during said semiconductor fabrication operation comprises a horizontal movement.

11. A method for preventing damage to a chamber wall by a baffle plate in a semiconductor fabrication system during a semiconductor fabrication operation, said method comprising the steps of:

moving an electrostatic chuck associated with said semiconductor fabrication system during said semiconductor fabrication operation; and

measuring a gap between said between said baffle plate and said chamber wall utilizing a gauge integrated with said semiconductor fabrication system, in response to moving said electrostatic chunk to thereby prevent damage to said chamber wall by said baffle plate.

12. The method of claim 11 wherein said semiconductor fabrication operation comprises a wet cleaning semiconductor operation.

13. The method of claim 11 wherein said gauge is adapted for use in leveling said electrostatic chunk.

14. The method of claim 11 wherein said gauge comprises a horizontal gap gauge.

15. The method of claim 11 wherein said gauge is adapted for use in preventing polymer peeling of said chamber wall.

16. The method of claim 11 wherein said gauge comprises a leveling gauge.

17. The method of claim 11 wherein said semiconductor fabrication system comprises dual-rotate-magnet (DRM).

18. The method of claim 17 wherein said semiconductor fabrication system comprises a focus ring.

19. The method of claim 18 wherein said movement of said electrostatic chunk during said semiconductor fabrication operation comprises a vertical movement.

20. The method of claim 18 wherein said movement of said electrostatic chunk during said semiconductor fabrication operation comprises a horizontal movement.